H-850G/H-850GP

Middle Tg, Halogen-free Laminate & Prepreg

产品特点

●无卤素阻燃，Tg150℃ （DSC）

●低 Z 軸膨脹系數和通孔可靠性

●优良的耐热和耐化学性能

●低吸水性， 耐 CAF 性能

●良好的尺寸安定性， 适用于 HDI 制程

应用领域

电脑、仪器仪表、通讯设备、游戏机、智能手机

行业标准

IPC4101E /128,UL94-V0,UL 号:E335867,RoHS

产品标准资料

基板厚度： 0.002"-0.126" (0.05-3.2mm)
标准尺寸： 37"*49"、41"*49"、43"*49"
铜箔厚度： 1/3-3OZ，或依客户要求
半固化片： 卷装或片状
玻璃布型号： 106-7630，或依客户要求

Key Features

●Halogen Free and Tg150℃(DSC)

●Low Z-CTE and excellent through hole reliability

●Excellent thermal stability and Chemical Resistance

●Low water absorption and Anti-CAF capability

●Good dimensional stability and used for HDI process

Applications

Computer, Instrumentation, Mobile Communication , Game machine, Smart Phone

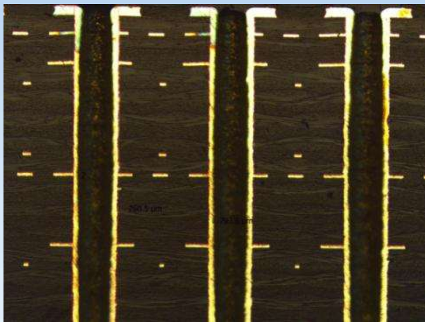
Industry approval

IPC4101E /128,UL94-V0,UL File Number:E335867,RoHS

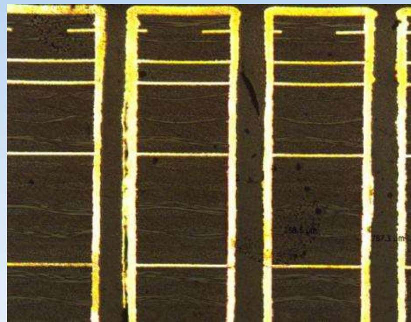
Standard Availability

Thickness:0.002"【0.05mm】to 0.126"【3.2mm】
Standard Size:37"*49",41"*49",43"*49"
Copper foil thinkness:1/3 to 3oz ,available on request
Prepreg:Available in roll or panel form
Glass style:Available on most Std style

信赖性能表现 Reliability Performance

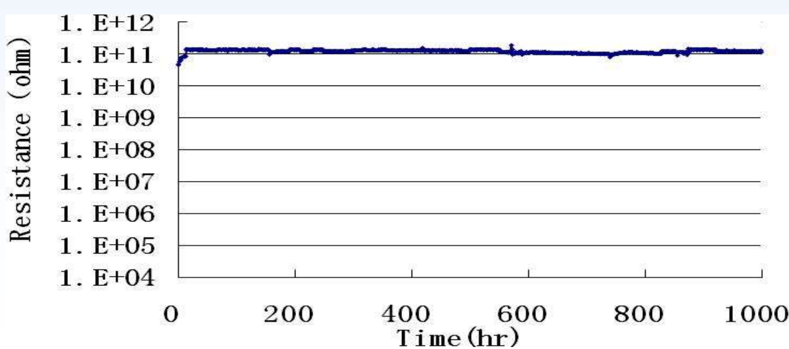


BGA



Cooling Hole

Migration Test Result



Test Conditions :

12 layer

Hole Diam : 0.35 mm

Pitch : 0.7 mm

Wall to Wall : 0.35 mm

Test Temp：85℃ / RH：85%

Bias ： 50DV

Test Result： ＞1000hr

General Properties

Property	Item		IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature		2.4.24.4	DSC	℃	150
	Z 轴方向膨胀系数 Z axis-CTE		2.4.24	TMA，Before TG	ppm/℃	35
				TMA，After TG	ppm/℃	220
				50～260℃	%	3.0
	288℃分层时间 T288		2.4.24.1	Clad	min	＞30
				Etched	min	＞30
	288℃热冲击 Thermal stress		2.6.8	288℃，solder dip	S	＞300
	热失重(weight loss 5%) Decomposition temperature		2.4.24.6	TGA	℃	360
电性能 Electrical	体积电阻 Volume Resistivity		2.5.17.1	C-96/35/90	MΩ-cm	＞10^{9}
	表面电阻 Surface Resistivity		2.5.17.1	C-96/35/90	MΩ	＞10^{10}
	Dk（RC50%）		2.5.5.9	1GHz;C-24/23/50	/	4.60
	Df（RC50%）		2.5.5.9	1GHz;C-24/23/50	/	0.011
	抗 CAF 性能 CAF Resistance		2.6.25	A	/	Pass
	击穿强度 Dielectric Breakdown		2.5.6	A	kV	60
	耐耐电弧性能 Arc Resistance		2.5.1	A	s	125
物理性能 Physical	弯曲强度 Flexural Strength	LW CW	2.4.4	A	MPa	510 450
	剥离强度 Peel Strength （Hoz Copper Foil）		2.4.8	288℃/10s	lb/inch	7.5
	阻燃等级 Flammability		UL94	UL94	/	V0
	吸水率 Moisture Absorption		2.6.2.1	D-24/23	%	0.19

The above data and fabrication guide provide designers and PCB shop for their reference. We believe that these information are accurate, however, the data may vary depend on the test methods and specification used. The actual sales of the product should be according to specification in the agreement between HINNO and its customer. HINNO reserves the right to revise its data at any time without notice and maintain the best information available to users